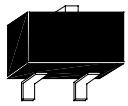
HBC846

NPN EPITAXIAL PLANAR TRANSISTOR



SOT-23

Description

The HBC846 is designed for switching and AF amplifier amplification suitable for automatic insertion in thick and thin-film circuits.

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature..... -55 to +150 °C
  Junction Temperature..... +150 °C
- Maximum Power Dissipation
  Total Power Dissipation (T_A=25°C)..... 225 mW
- Maximum Voltages and Currents (T_A=25°C)
  V_{CBO} Collector to Base Voltage..... 80 V
  V_{CEO} Collector to Emitter Voltage..... 65 V
  V_{EBO} Emitter to Base Voltage..... 6 V
  I_C Collector Current ..... 100 mA

Electrical Characteristics (T_A=25°C)

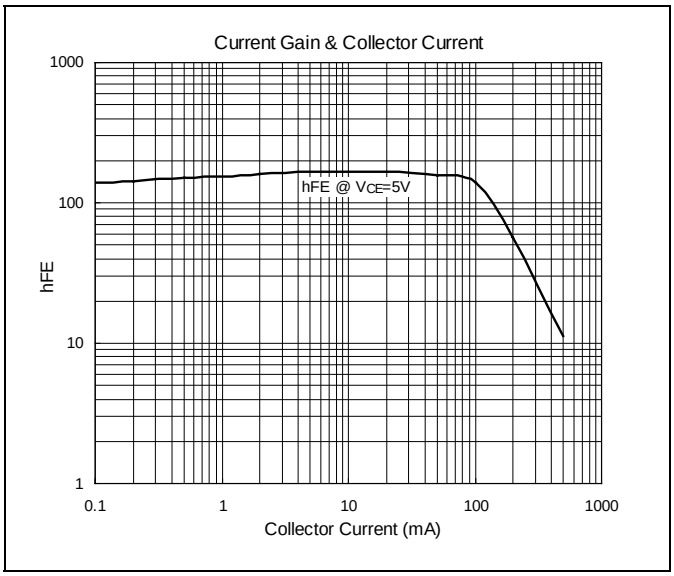
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	80	-	-	V	I_C=100uA
BV_{CEO}	65	-	-	V	I_C=1mA
BV_{EBO}	6	-	-	V	I_E=10uA
I_{CBO}	-	-	15	nA	V_{CB}=30V
*$V_{CE(sat)1}$	-	90	250	mV	I_C=10mA, I_B=0.5mA
*$V_{CE(sat)2}$	-	200	600	mV	I_C=100mA, I_B=5mA
*$V_{BE(sat)1}$	-	700	-	mV	I_C=10mA, I_B=0.5mA
*$V_{BE(sat)2}$	-	900	-	mV	I_C=100mA, I_B=5mA
$V_{BE(on)1}$	580	-	700	mV	V_{CE}=5V, I_C=2mA
$V_{BE(on)2}$	-	-	770	mV	V_{CE}=5V, I_C=10mA
*h_{FE}	110	-	800		V_{CE}=5V, I_C=2mA
f_T	-	300	-	MHz	V_{CE}=5V, I_C=10mA
Cob	-	3.5	6	pF	V_{CB}=10V, f=1MHz, I_E=0

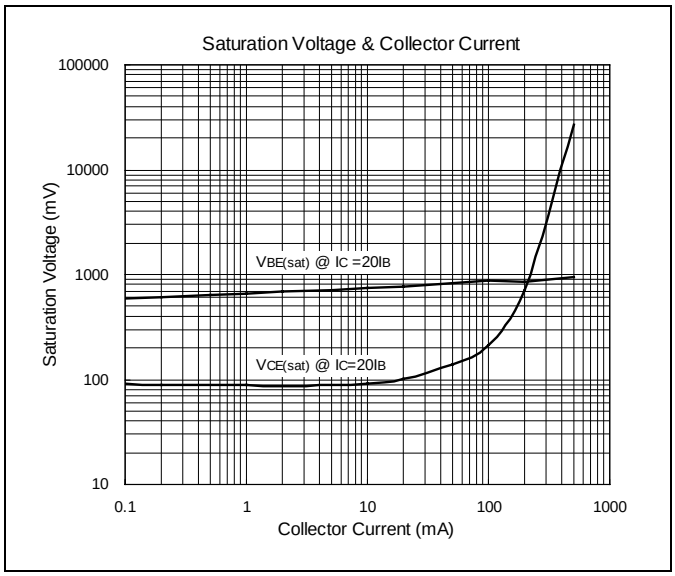
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

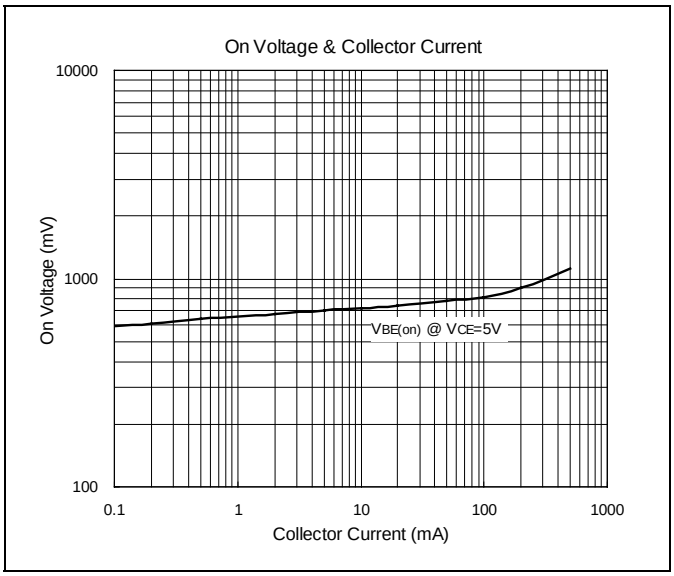
Classification Of hFE

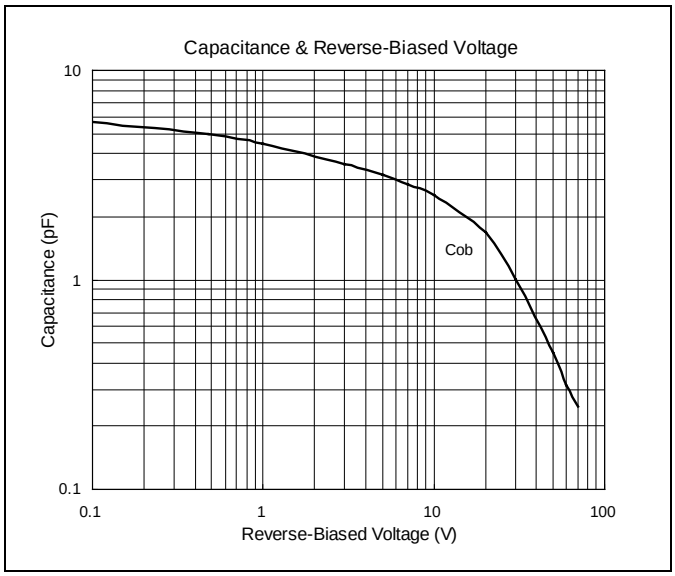
Rank	8AA(A)	8AB(B)	8AC(C)
hFE	110-220	200-450	420-800

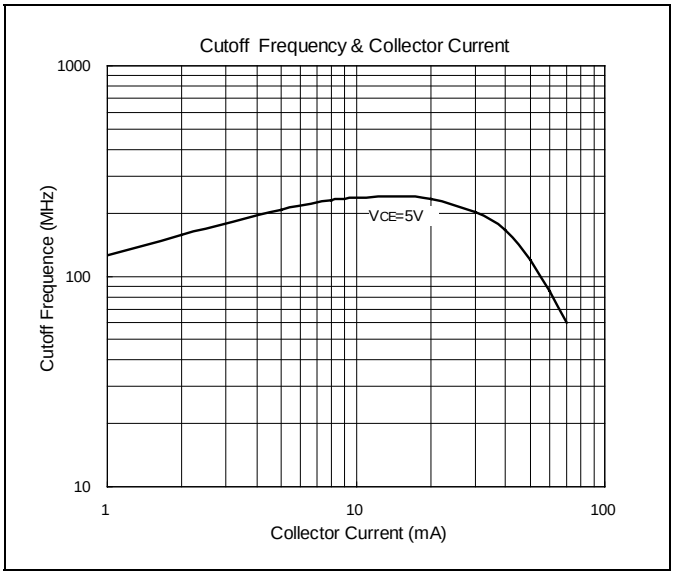
Characteristics Curve

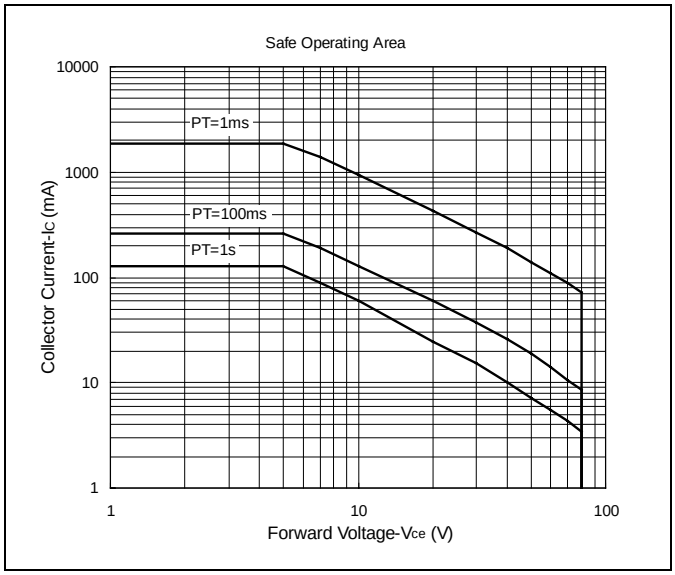




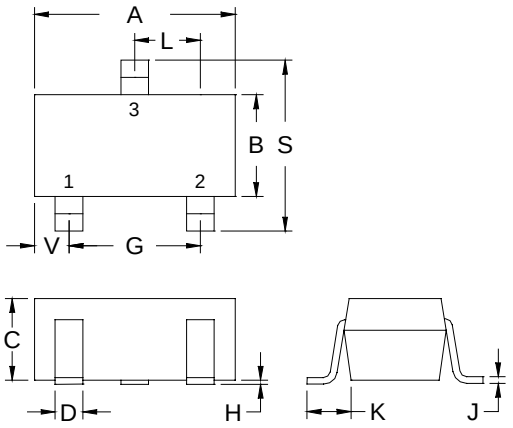






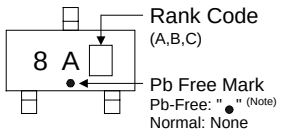


SOT-23 Dimension



3-Lead SOT-23 Plastic
Surface Mounted Package
HSMC Package Code: N

Marking:



Note: Pb-free product can distinguish by the green label or the extra description on the right side of the label.

Pin Style: 1.Base 2.Emitter 3.Collector

Material:
- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	2.80	3.04
B	1.20	1.60
C	0.89	1.30
D	0.30	0.50
G	1.70	2.30
H	0.013	0.10
J	0.085	0.177
K	0.32	0.67
L	0.85	1.15
S	2.10	2.75
V	0.25	0.65

*: Typical, Unit: mm

Head Office And Factory:

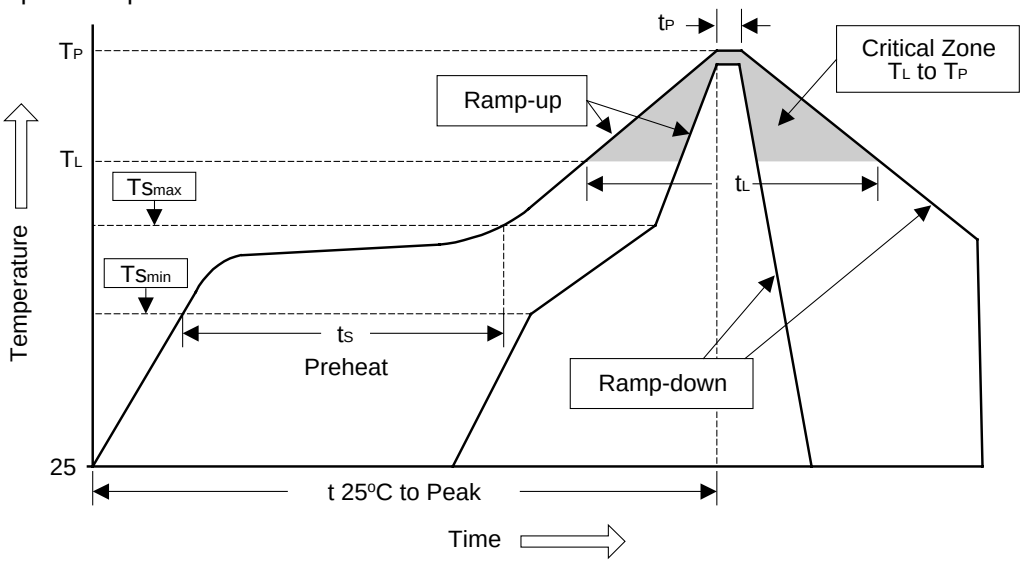
- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
  Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel: 886-3-5983621~5 Fax: 886-3-5982931

Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%

2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (min to max) (ts)	 100°C 150°C 60~120 sec	 150°C 200°C 60~180 sec
Tsmax to T_L - Ramp-up Rate	 <3°C/sec	 <3°C/sec
Time maintained above: - Temperature (T_L) - Time (t_L)	 183°C 60~150 sec	 217°C 60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec